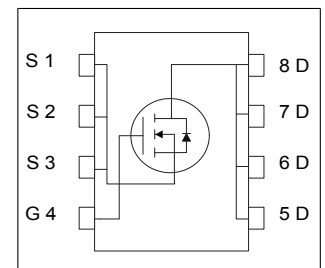
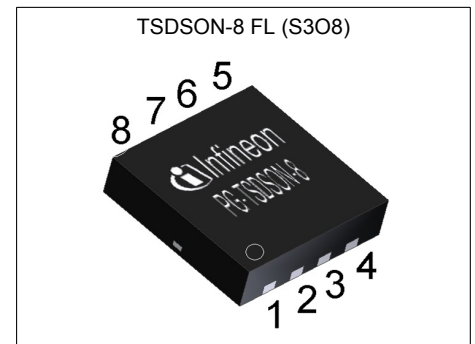


# MOSFET

## OptiMOS™ Power-MOSFET, 30 V

### Features

- Optimized for high performance Buck converter (Server,VGA)
- Very Low  $FOM_{QOSS}$  for High Frequency SMPS
- Low  $FOM_{SW}$  for High Frequency SMPS
- Excellent gate charge x  $R_{DS(on)}$  product (FOM)
- Very low on-resistance  $R_{DS(on)}$  @  $V_{GS}=4.5$  V
- 100% avalanche tested
- Superior thermal resistance
- N-channel
- Qualified according to JEDEC<sup>1)</sup> for target applications
- Pb-free lead plating; RoHS compliant
- Halogen-free according to IEC61249-2-21



RoHS

**Table 1 Key Performance Parameters**

| Parameter        | Value | Unit       |
|------------------|-------|------------|
| $V_{DS}$         | 30    | V          |
| $R_{DS(on),max}$ | 1.9   | m $\Omega$ |
| $I_D$            | 149   | A          |
| $Q_{OSS}$        | 25    | nC         |
| $Q_G(0V..10V)$   | 44    | nC         |

| Type / Ordering Code | Package        | Marking | Related Links |
|----------------------|----------------|---------|---------------|
| BSZ019N03LS          | PG-TSDSON-8 FL | 019N03L | -             |

<sup>1)</sup> J-STD20 and JESD22

## Table of Contents

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## 1 Maximum ratings

at  $T_A=25\text{ °C}$ , unless otherwise specified

**Table 2 Maximum ratings**

| Parameter                                     | Symbol            | Values |      |      | Unit | Note / Test Condition   |
|---|-------------------|--------|------|------|------|---|
|   |                   | Min.   | Typ. | Max. |      |   |
| Continuous drain current <sup>1)</sup>        | $I_D$             | -      | -    | 149  | A    | $V_{GS}=10\text{ V}$ , $T_C=25\text{ °C}$<br>$V_{GS}=10\text{ V}$ , $T_C=100\text{ °C}$<br>$V_{GS}=4.5\text{ V}$ , $T_C=25\text{ °C}$<br>$V_{GS}=4.5\text{ V}$ , $T_C=100\text{ °C}$<br>$V_{GS}=4.5\text{ V}$ , $T_A=25\text{ °C}$ , $R_{thJA}=60\text{ K/W}$ |
|   |                   | -      | -    | 94   |      |   |
|   |                   | -      | -    | 130  |      |   |
|   |                   | -      | -    | 82   |      |   |
|   |                   | -      | -    | 22   |      |   |
| Pulsed drain current <sup>2)</sup>            | $I_{D,pulse}$     | -      | -    | 596  | A    | $T_C=25\text{ °C}$  |
| Avalanche current, single pulse <sup>3)</sup> | $I_{AS}$          | -      | -    | 20   | A    | $T_C=25\text{ °C}$  |
| Avalanche energy, single pulse                | $E_{AS}$          | -      | -    | 150  | mJ   | $I_D=20\text{ A}$ , $R_{GS}=25\text{ }\Omega$   |
| Gate source voltage                           | $V_{GS}$          | -20    | -    | 20   | V    | -   |
| Power dissipation                             | $P_{tot}$         | -      | -    | 69   | W    | $T_C=25\text{ °C}$<br>$T_A=25\text{ °C}$ , $R_{thJA}=60\text{ K/W}$   |
|   |                   | -      | -    | 2.1  |      |   |
| Operating and storage temperature             | $T_j$ , $T_{stg}$ | -55    | -    | 150  | °C   | IEC climatic category;<br>DIN IEC 68-1: 55/150/56   |

## 2 Thermal characteristics

**Table 3 Thermal characteristics**

| Parameter  | Symbol     | Values |      |      | Unit | Note / Test Condition |
|--|------------|--------|------|------|------|-----------------------|
|  |            | Min.   | Typ. | Max. |      |                       |
| Thermal resistance, junction - case                            | $R_{thJC}$ | -      | -    | 1.8  | K/W  | -                     |
| Device on PCB,<br>6 cm <sup>2</sup> cooling area <sup>4)</sup> | $R_{thJA}$ | -      | -    | 60   | K/W  | -                     |

<sup>1)</sup> Rating refers to the product only with datasheet specified absolute maximum values, maintaining case temperature at 25°C. For higher case temperature please refer to Diagram 2. De-rating will be required based on the actual environmental conditions.

<sup>2)</sup> See Diagram 3 for more detailed information

<sup>3)</sup> See Diagram 13 for more detailed information

<sup>4)</sup> Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm<sup>2</sup> (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.

### 3 Electrical characteristics

at  $T_j=25\text{ °C}$ , unless otherwise specified

**Table 4 Static characteristics**

| Parameter                        | Symbol        | Values |            |            | Unit             | Note / Test Condition   |
|----------------------------------|---------------|--------|------------|------------|------------------|---|
|                                  |               | Min.   | Typ.       | Max.       |                  |   |
| Drain-source breakdown voltage   | $V_{(BR)DSS}$ | 30     | -          | -          | V                | $V_{GS}=0\text{ V}$ , $I_D=1\text{ mA}$   |
| Gate threshold voltage           | $V_{GS(th)}$  | 1.2    | -          | 2          | V                | $V_{DS}=V_{GS}$ , $I_D=250\text{ }\mu\text{A}$  |
| Zero gate voltage drain current  | $I_{DSS}$     | -      | 0.1<br>10  | 1<br>100   | $\mu\text{A}$    | $V_{DS}=30\text{ V}$ , $V_{GS}=0\text{ V}$ , $T_j=25\text{ °C}$<br>$V_{DS}=30\text{ V}$ , $V_{GS}=0\text{ V}$ , $T_j=125\text{ °C}$ |
| Gate-source leakage current      | $I_{GSS}$     | -      | 10         | 100        | nA               | $V_{GS}=20\text{ V}$ , $V_{DS}=0\text{ V}$  |
| Drain-source on-state resistance | $R_{DS(on)}$  | -      | 2.0<br>1.6 | 2.5<br>1.9 | $\text{m}\Omega$ | $V_{GS}=4.5\text{ V}$ , $I_D=20\text{ A}$<br>$V_{GS}=10\text{ V}$ , $I_D=20\text{ A}$   |
| Gate resistance                  | $R_G$         | 0.4    | 0.8        | 1.6        | $\Omega$         | -   |
| Transconductance                 | $g_{fs}$      | 70     | 140        | -          | S                | $ V_{DS} >2 I_D R_{DS(on)max}$ , $I_D=30\text{ A}$  |

**Table 5 Dynamic characteristics**

| Parameter                        | Symbol       | Values |      |      | Unit | Note / Test Condition  |
|----------------------------------|--------------|--------|------|------|------|--|
|                                  |              | Min.   | Typ. | Max. |      |  |
| Input capacitance <sup>1)</sup>  | $C_{iss}$    | -      | 2800 | 3800 | pF   | $V_{GS}=0\text{ V}$ , $V_{DS}=15\text{ V}$ , $f=1\text{ MHz}$                                      |
| Output capacitance <sup>1)</sup> | $C_{oss}$    | -      | 960  | 1300 | pF   | $V_{GS}=0\text{ V}$ , $V_{DS}=15\text{ V}$ , $f=1\text{ MHz}$                                      |
| Reverse transfer capacitance     | $C_{rss}$    | -      | 140  | -    | pF   | $V_{GS}=0\text{ V}$ , $V_{DS}=15\text{ V}$ , $f=1\text{ MHz}$                                      |
| Turn-on delay time               | $t_{d(on)}$  | -      | 5.4  | -    | ns   | $V_{DD}=15\text{ V}$ , $V_{GS}=10\text{ V}$ , $I_D=30\text{ A}$ ,<br>$R_{G,ext}=1.6\text{ }\Omega$ |
| Rise time                        | $t_r$        | -      | 6.8  | -    | ns   | $V_{DD}=15\text{ V}$ , $V_{GS}=10\text{ V}$ , $I_D=30\text{ A}$ ,<br>$R_{G,ext}=1.6\text{ }\Omega$ |
| Turn-off delay time              | $t_{d(off)}$ | -      | 28   | -    | ns   | $V_{DD}=15\text{ V}$ , $V_{GS}=10\text{ V}$ , $I_D=30\text{ A}$ ,<br>$R_{G,ext}=1.6\text{ }\Omega$ |
| Fall time                        | $t_f$        | -      | 4.6  | -    | ns   | $V_{DD}=15\text{ V}$ , $V_{GS}=10\text{ V}$ , $I_D=30\text{ A}$ ,<br>$R_{G,ext}=1.6\text{ }\Omega$ |

**Table 6 Gate charge characteristics<sup>2)</sup>**

| Parameter                           | Symbol        | Values |      |      | Unit | Note / Test Condition  |
|-------------------------------------|---------------|--------|------|------|------|--|
|                                     |               | Min.   | Typ. | Max. |      |  |
| Gate to source charge <sup>1)</sup> | $Q_{gs}$      | -      | 7.0  | 9.3  | nC   | $V_{DD}=15\text{ V}$ , $I_D=30\text{ A}$ , $V_{GS}=0\text{ to }4.5\text{ V}$ |
| Gate charge at threshold            | $Q_{g(th)}$   | -      | 4.6  | -    | nC   | $V_{DD}=15\text{ V}$ , $I_D=30\text{ A}$ , $V_{GS}=0\text{ to }4.5\text{ V}$ |
| Gate to drain charge <sup>1)</sup>  | $Q_{gd}$      | -      | 6.5  | 8.5  | nC   | $V_{DD}=15\text{ V}$ , $I_D=30\text{ A}$ , $V_{GS}=0\text{ to }4.5\text{ V}$ |
| Switching charge                    | $Q_{sw}$      | -      | 9.0  | -    | nC   | $V_{DD}=15\text{ V}$ , $I_D=30\text{ A}$ , $V_{GS}=0\text{ to }4.5\text{ V}$ |
| Gate charge total <sup>1)</sup>     | $Q_g$         | -      | 22   | 29   | nC   | $V_{DD}=15\text{ V}$ , $I_D=30\text{ A}$ , $V_{GS}=0\text{ to }4.5\text{ V}$ |
| Gate plateau voltage                | $V_{plateau}$ | -      | 2.5  | -    | V    | $V_{DD}=15\text{ V}$ , $I_D=30\text{ A}$ , $V_{GS}=0\text{ to }4.5\text{ V}$ |
| Gate charge total <sup>1)</sup>     | $Q_g$         | -      | 44   | 59   | nC   | $V_{DD}=15\text{ V}$ , $I_D=30\text{ A}$ , $V_{GS}=0\text{ to }10\text{ V}$  |
| Gate charge total, sync. FET        | $Q_{g(sync)}$ | -      | 18   | -    | nC   | $V_{DS}=0.1\text{ V}$ , $V_{GS}=0\text{ to }4.5\text{ V}$                    |
| Output charge <sup>1)</sup>         | $Q_{oss}$     | -      | 25   | 33   | nC   | $V_{DD}=15\text{ V}$ , $V_{GS}=0\text{ V}$                                   |

<sup>1)</sup> Defined by design. Not subject to production test

<sup>2)</sup> See "Gate charge waveforms" for parameter definition

**Table 7 Reverse diode**

| Parameter                        | Symbol        | Values |      |      | Unit | Note / Test Condition  |
|----------------------------------|---------------|--------|------|------|------|--|
|                                  |               | Min.   | Typ. | Max. |      |  |
| Diode continuous forward current | $I_S$         | -      | -    | 69   | A    | $T_C=25\text{ °C}$   |
| Diode pulse current              | $I_{S,pulse}$ | -      | -    | 596  | A    | $T_C=25\text{ °C}$   |
| Diode forward voltage            | $V_{SD}$      | -      | 0.8  | 1    | V    | $V_{GS}=0\text{ V}, I_F=20\text{ A}, T_j=25\text{ °C}$       |
| Reverse recovery charge          | $Q_{rr}$      | -      | 20   | -    | nC   | $V_R=15\text{ V}, I_F=I_S, di_F/dt=400\text{ A}/\mu\text{s}$ |

### 4 Electrical characteristics diagrams

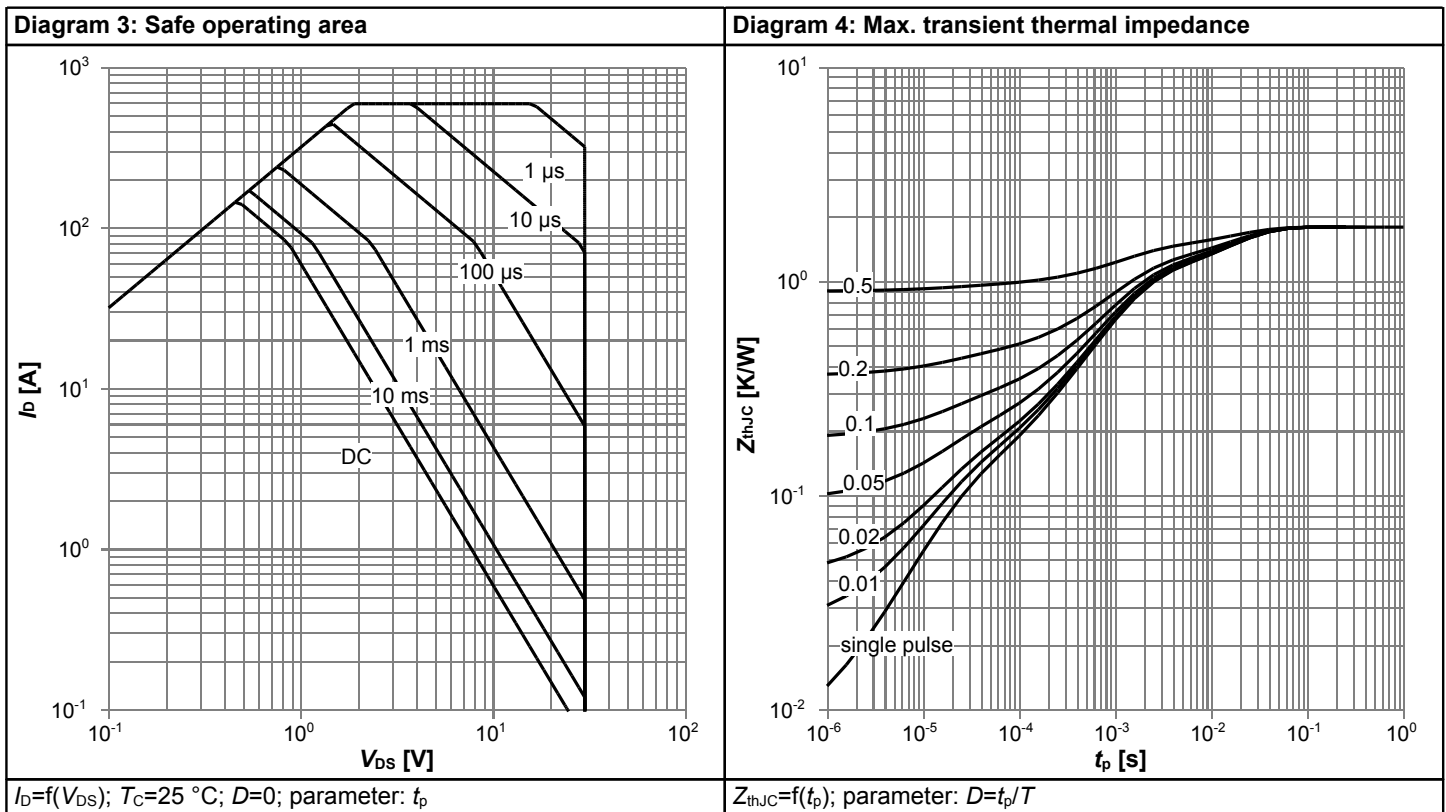
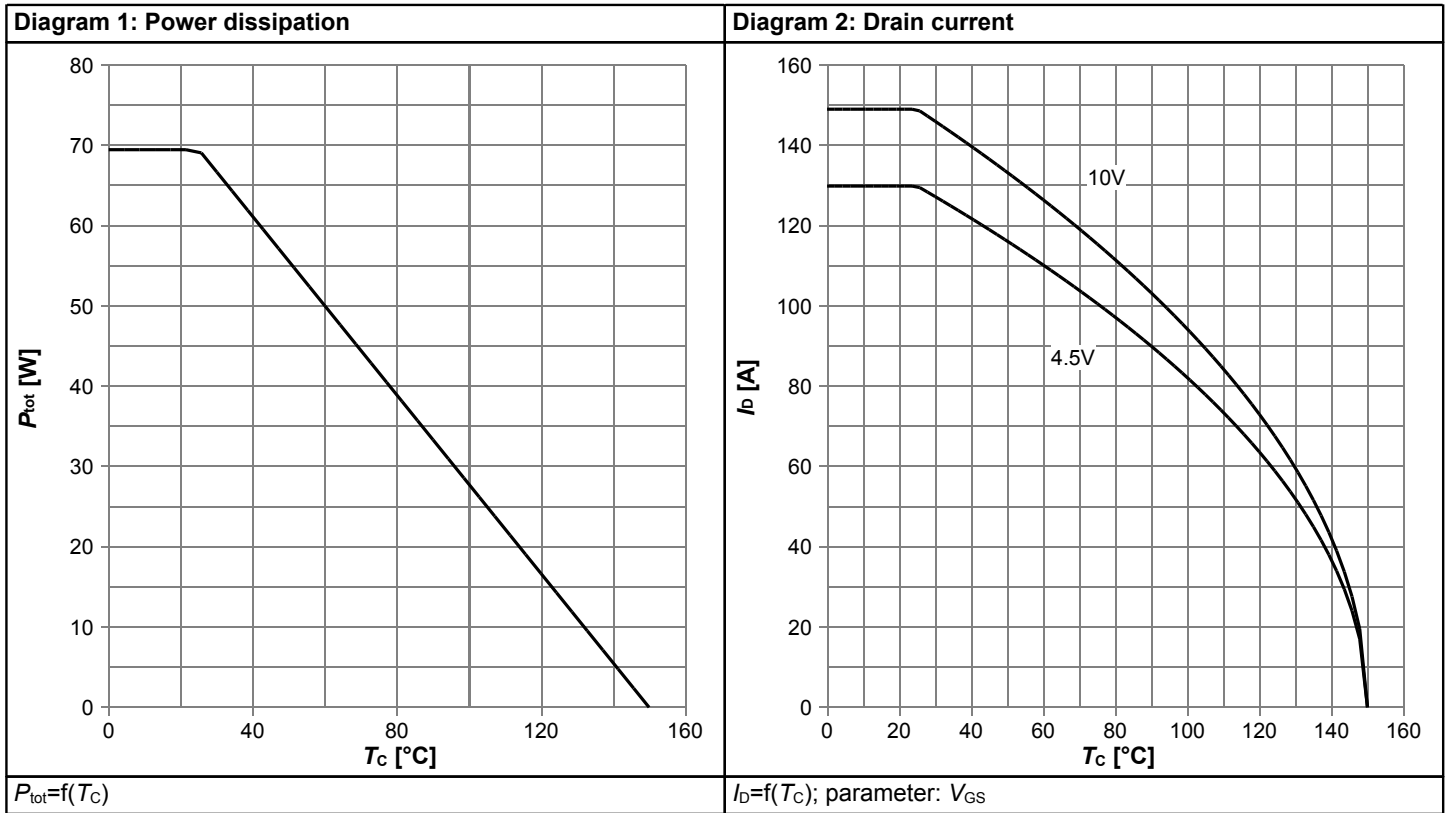
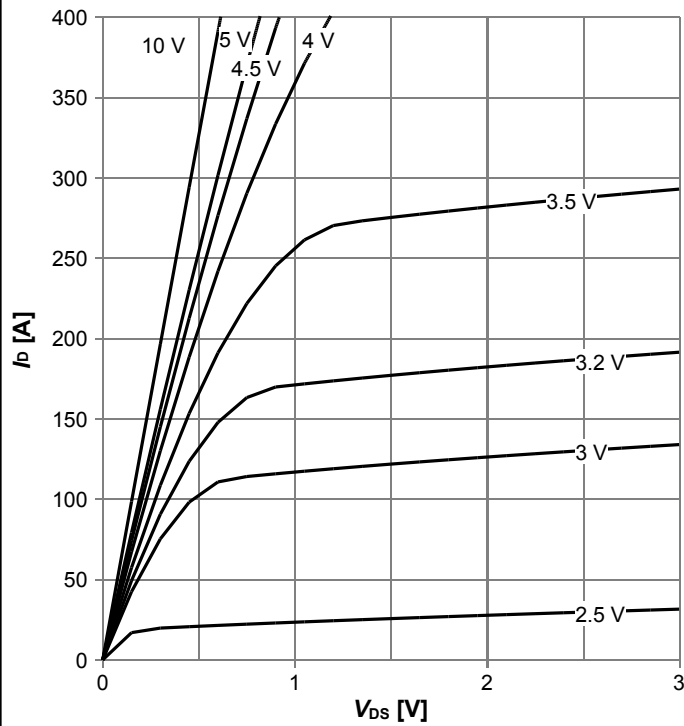
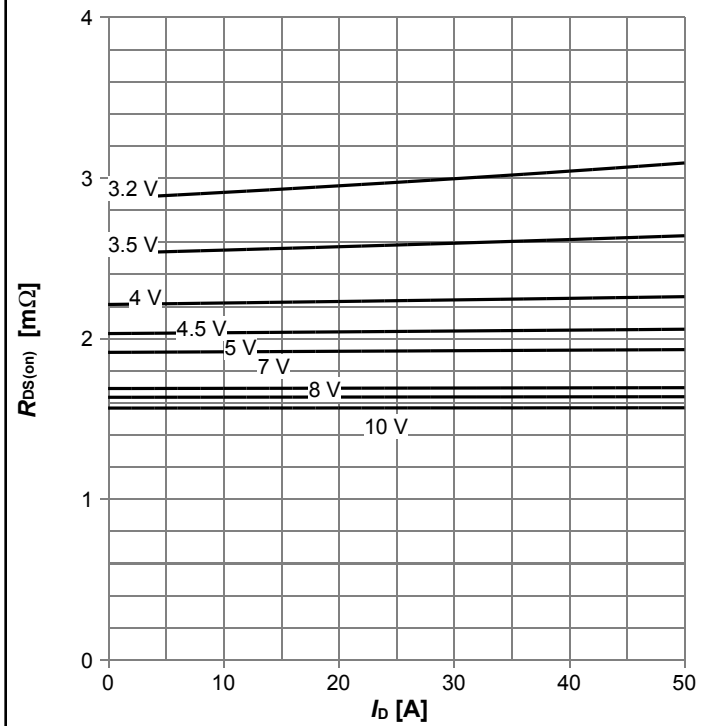


Diagram 5: Typ. output characteristics



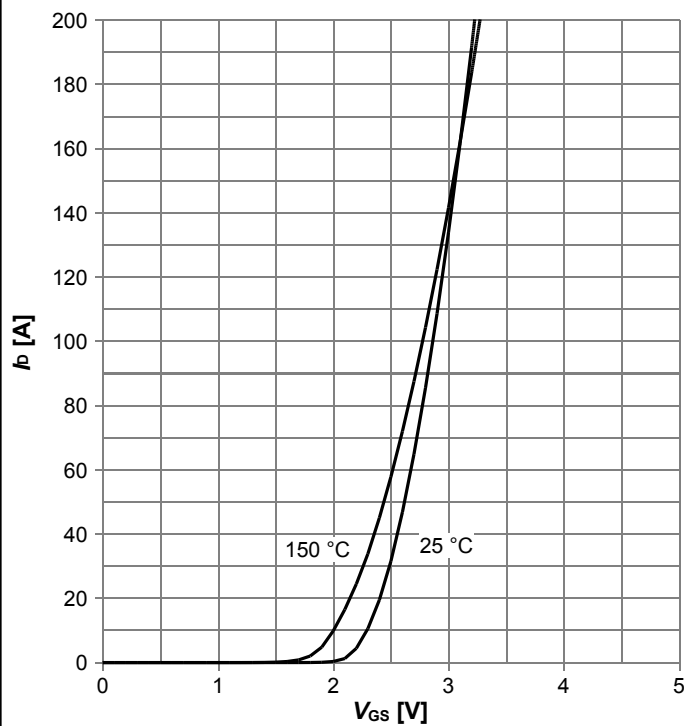
$I_D = f(V_{DS}); T_j = 25\text{ °C}; \text{parameter: } V_{GS}$

Diagram 6: Typ. drain-source on resistance



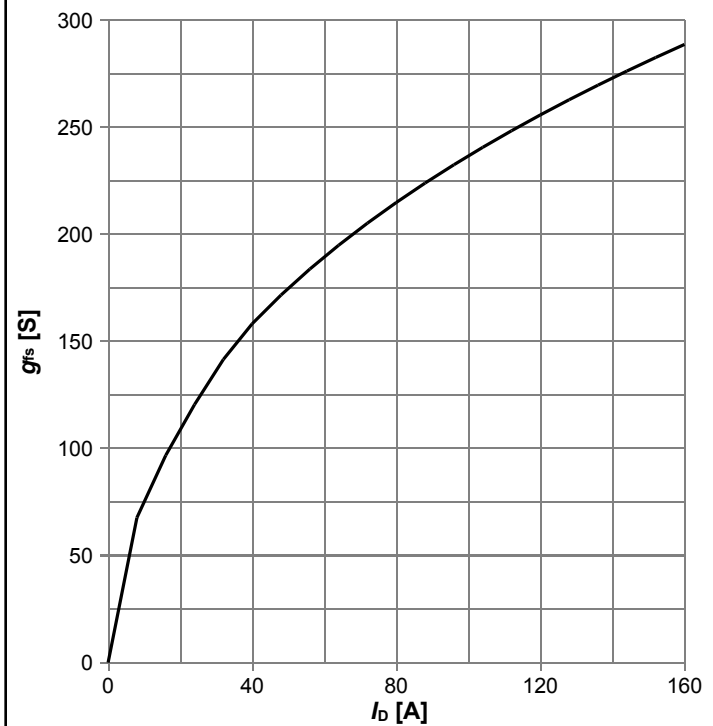
$R_{DS(on)} = f(I_D); T_j = 25\text{ °C}; \text{parameter: } V_{GS}$

Diagram 7: Typ. transfer characteristics



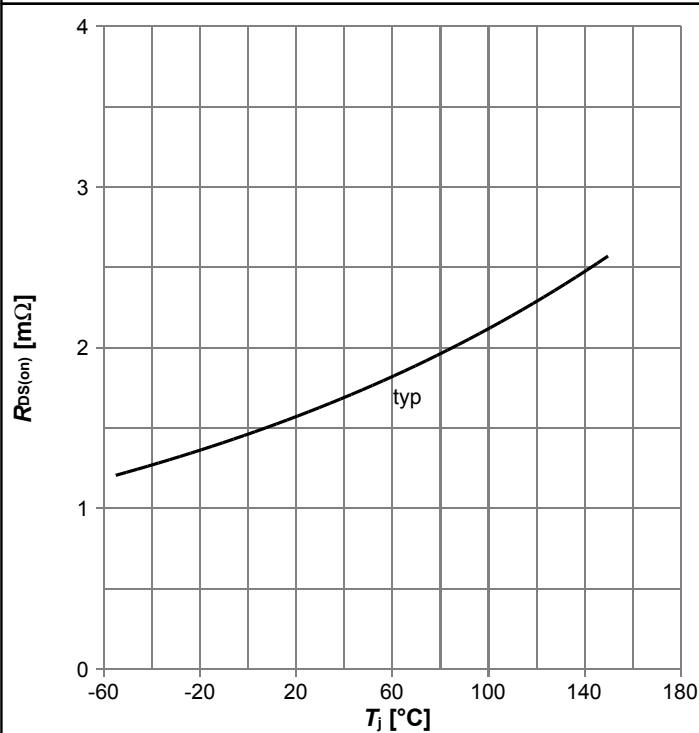
$I_D = f(V_{GS}); |V_{DS}| > 2|I_D|R_{DS(on)max}; \text{parameter: } T_j$

Diagram 8: Typ. forward transconductance



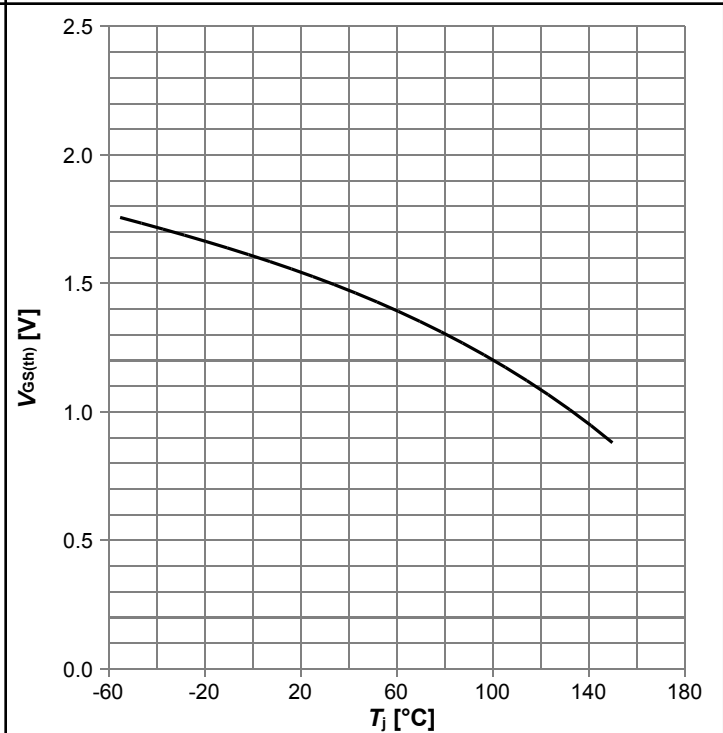
$g_{fs} = f(I_D); T_j = 25\text{ °C}$

Diagram 9: Drain-source on-state resistance



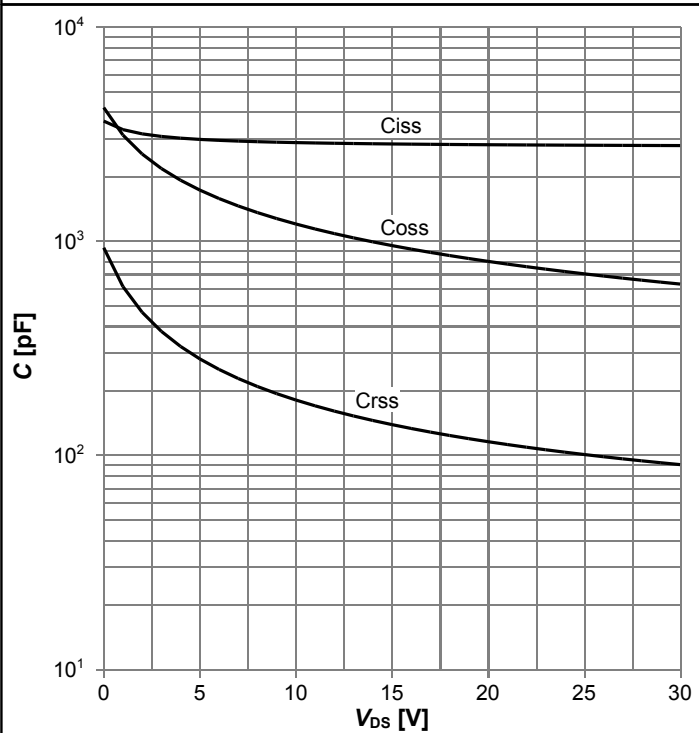
$R_{DS(on)}=f(T_j)$ ;  $I_D=30$  A;  $V_{GS}=10$  V

Diagram 10: Typ. gate threshold voltage



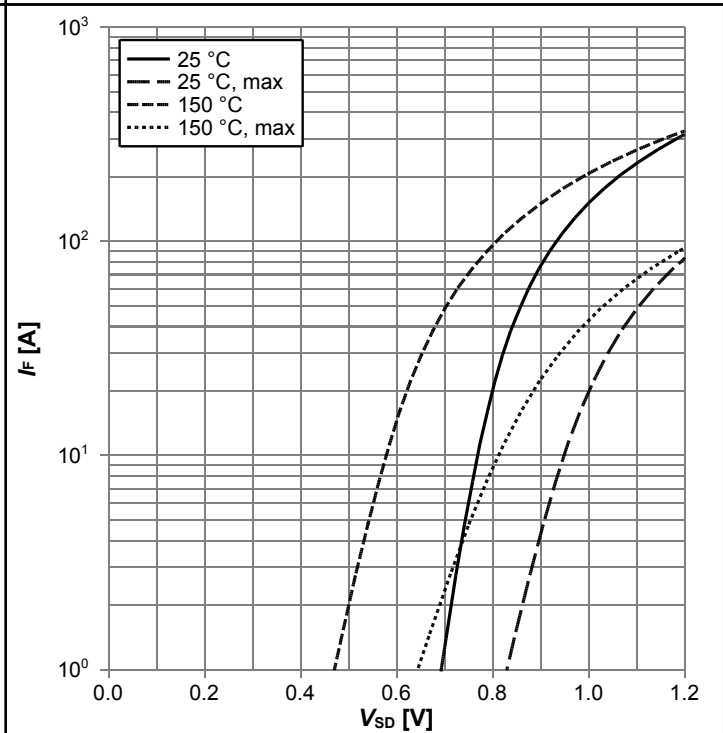
$V_{GS(th)}=f(T_j)$ ;  $V_{GS}=V_{DS}$ ;  $I_D=250$  μA

Diagram 11: Typ. capacitances



$C=f(V_{DS})$ ;  $V_{GS}=0$  V;  $f=1$  MHz

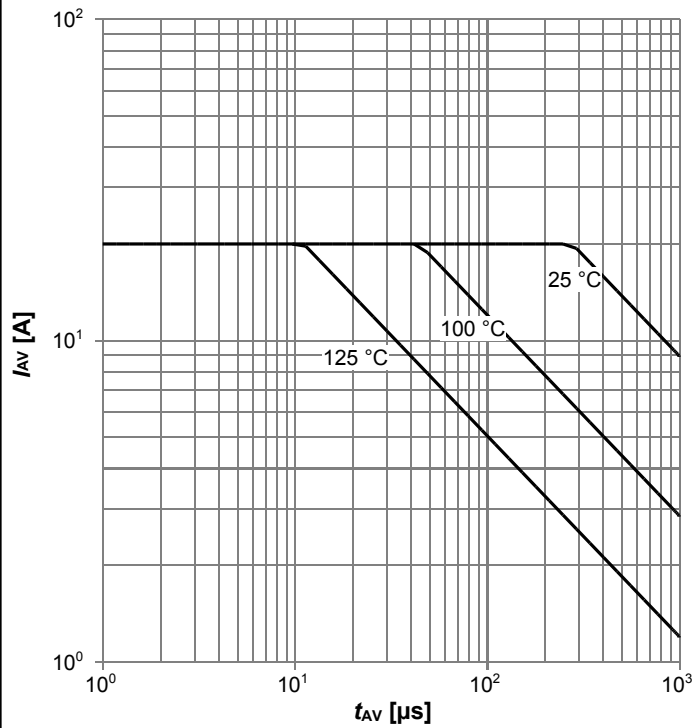
Diagram 12: Forward characteristics of reverse diode



$I_F=f(V_{SD})$ ; parameter:  $T_j$

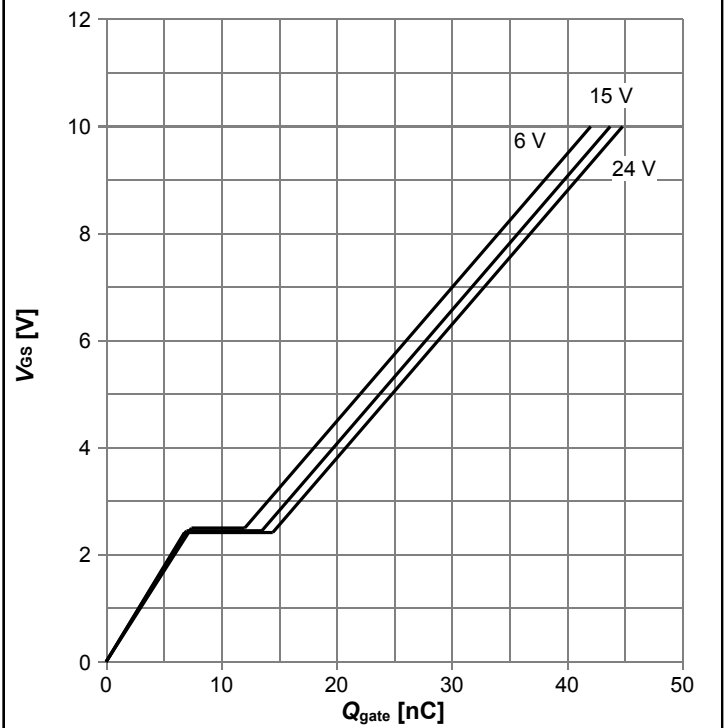


Diagram 13: Avalanche characteristics



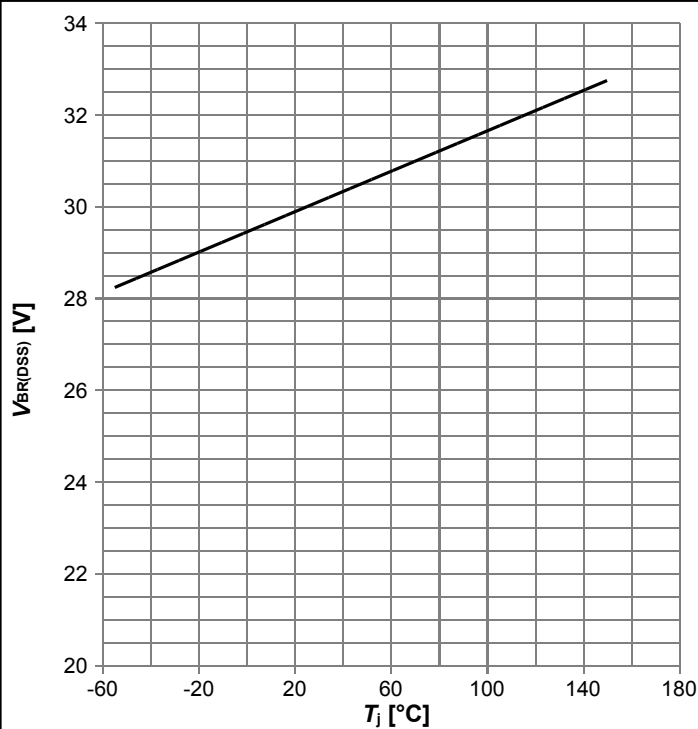
$I_{AS}=f(t_{AV}); R_{GS}=25 \Omega$ ; parameter:  $T_{j(start)}$

Diagram 14: Typ. gate charge



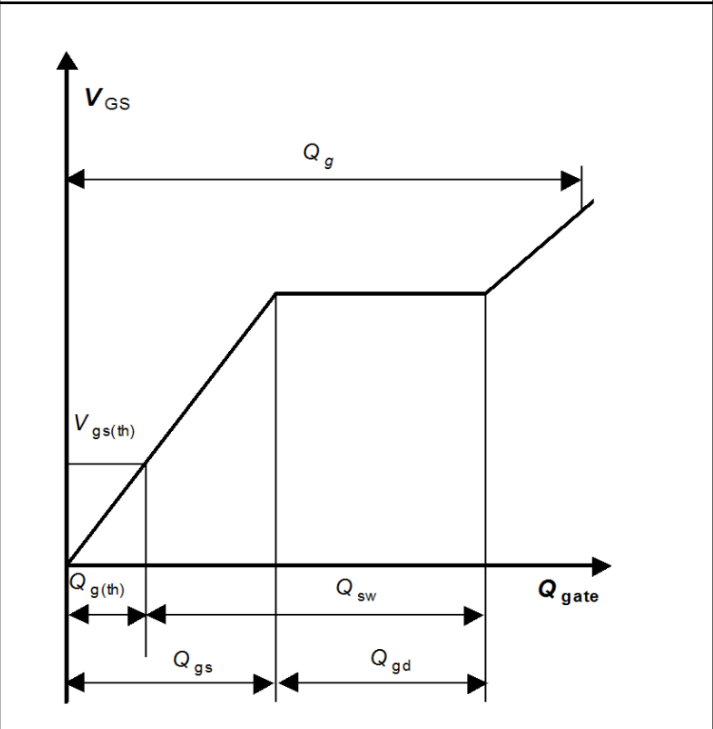
$V_{GS}=f(Q_{gate}); I_D=30 \text{ A pulsed}$ ; parameter:  $V_{DD}$

Diagram 15: Drain-source breakdown voltage

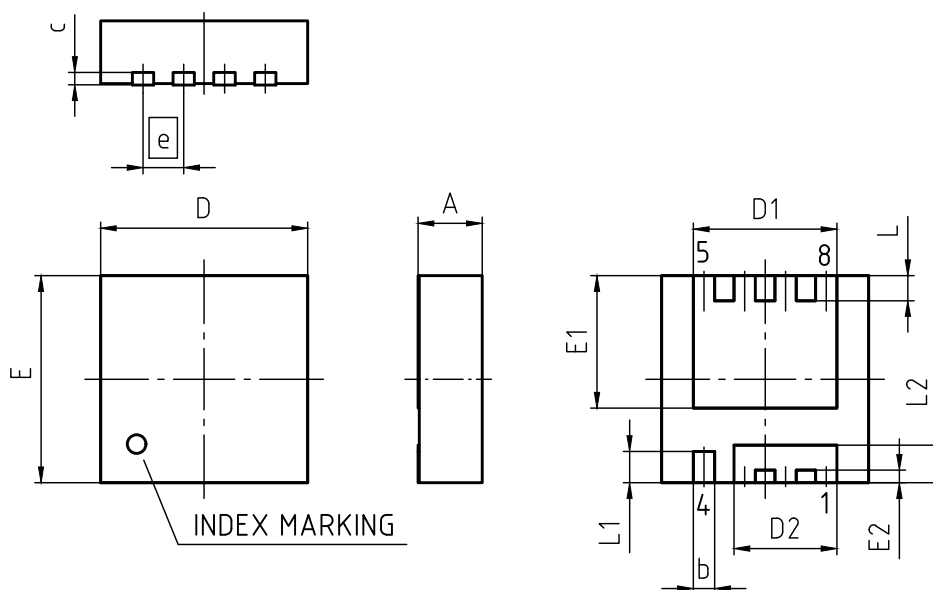


$V_{BR(DSS)}=f(T_j); I_D=1 \text{ mA}$

Diagram Gate charge waveforms



## 5 Package Outlines



| PACKAGE - GROUP NUMBER: <b>PG-TSDSON-8-U03</b> |                  |      |
|--|------------------|------|
| REVISION: 03                                   | DATE: 20.10.2020 |      |
| DIMENSIONS                                     | MILLIMETERS      |      |
|  | MIN.             | MAX. |
| <b>A</b>                                       | 0.90             | 1.10 |
| <b>b</b>                                       | 0.24             | 0.44 |
| <b>c</b>                                       | (0.20)           |      |
| <b>D</b>                                       | 3.20             | 3.40 |
| <b>D1</b>                                      | 2.19             | 2.39 |
| <b>D2</b>                                      | 1.54             | 1.74 |
| <b>E</b>                                       | 3.20             | 3.40 |
| <b>E1</b>                                      | 2.01             | 2.21 |
| <b>E2</b>                                      | 0.10             | 0.30 |
| <b>e</b>                                       | 0.65             |      |
| <b>L</b>                                       | 0.30             | 0.50 |
| <b>L1</b>                                      | 0.40             | 0.60 |
| <b>L2</b>                                      | 0.50             | 0.70 |
| <b>aaa</b>                                     | 0.06             |      |

Figure 1 Outline PG-TSDSON-8 FL, dimensions in mm

## Revision History

BSZ019N03LS

**Revision: 2020-11-13, Rev. 2.4**

Previous Revision

| Revision | Date       | Subjects (major changes since last revision) |
|----------|------------|--|
| 2.3      | 2020-08-12 | Update current rating and footnotes          |
| 2.4      | 2020-11-13 | Update package drawing                       |

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